

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Hsin-Chieh Yo	05/17/2010
Hsien-Cheng Wang	05/19/2010
Chun-Kuang Chen	05/19/2010
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. 6, Science Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12784581
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	972-739-8635
Email:	saadia.cooks@haynesboone.com
Correspondent Name:	David M. O'Dell
Address Line 1:	HAYNES AND BOONE, LLP.
Address Line 2:	2323 Victory Avenue, Suite 700
Address Line 4:	Dallas, TEXAS 75219
ATTORNEY DOCKET NUMBER:	24061.1449
NAME OF SUBMITTER:	David M. O'Dell

Total Attachments: 3
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Docket No.: 2010-0100 / 24061.1449
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- (1) Hsin-Chieh Yao of No. 1, Lane 57, Minli Street
Yunlin County 640, Taiwan, R.O.C.
- (2) Hsien-Cheng Wang of 13F-1, No. 373, Sec. 2, Gong-Dao 5 Road
Hsinchu 300, Taiwan, R.O.C.
- (3) ~~Huang Chien Kai~~ of ~~8F-2, No. 88, Sec. 1, Xifeng 11th Road~~
~~Zhubei City, Maimohu County 302, Taiwan, R.O.C.~~
- (4) Chun-Kuang Chen of No. 122, Yu-Hsien Street, Guan-Shi Jeng
Hsin-Chu Hsien, Taiwan, R.O.C.

have invented certain improvements in

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for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on May 21, 2010 and
assigned application number 12/784,581; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

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AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Hsin-Chieh Yao

Residence Address: No. 1, Lane 57, Minli Street Townshipshan District
Yunlin County 640, Taiwan, R.O.C.

Dated: 2010.05.17

Hsin-Chieh Yao
Inventor Signature

Inventor Name: Hsien-Cheng Wang

Residence Address: 13F-1, No. 373, Sec. 2, Gong-Dao 5 Road
Hsinchu 300, Taiwan, R.O.C.

Dated: May, 19, 2010

Hsien-Cheng Wang
Inventor Signature

~~Inventor Name: Huang Chien Kai~~

~~Residence Address: 8F-2, No. 23, Sec. 1, Jiafeng 1st Road
Zhubei City, Hsinchu County 302, Taiwan, R.O.C.~~

~~Dated: Huang Chien Kai
2010.05.17~~

~~Huang Chien Kai
Inventor Signature~~

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Inventor Name: Chun-Kuang Chen

Residence Address: No. 122, Yu-Hsien Street, Guan-Shi Jeng
Hsin-Chu Hsien, Taiwan, R.O.C.

Dated: 2010.5.19

Chun-Kuang Chen
Inventor Signature